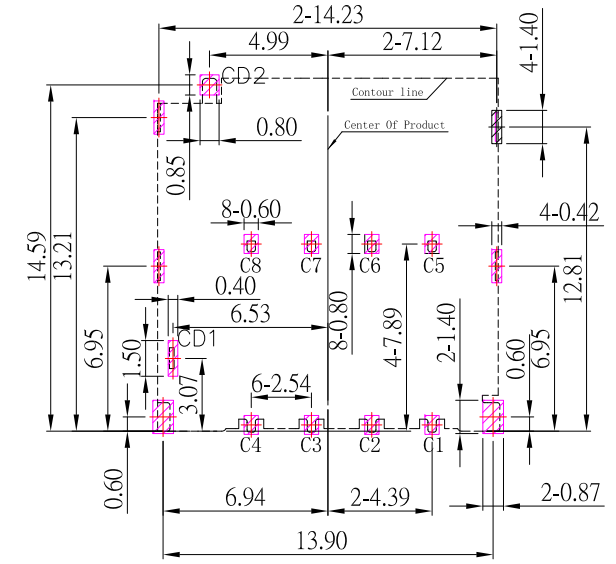
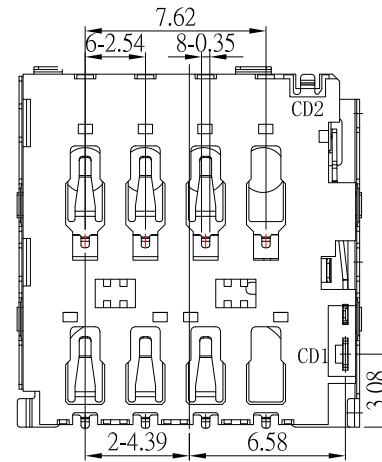
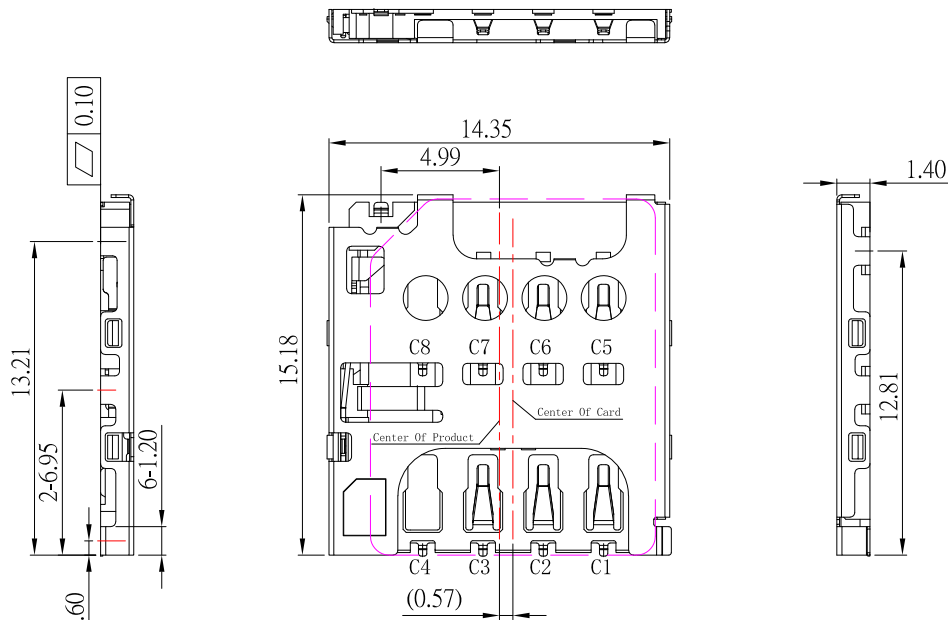
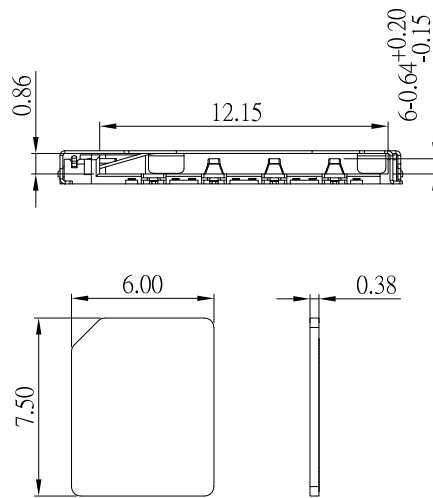
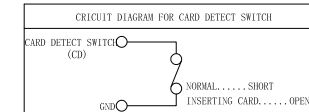




P.C.B LAYOUT



PIN/NO	ASSIGNMENT
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved
CD1	Detect Switch
CD2	Detect Switch

NOTES:

1) MATERIAL:

1.1 HOUSING: LCP

1.2 CONTACT: PHOSPHOR BRONZE

1.3 SHELL: SUS

2) FINISH:

2.1 CONTACT: PLATED GOLD IN MATING AREA ;

GOLD PLATED ON SOLDER BALLS ;

NICKEL UNDER PLATED OVERALL

2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER

3) ELECTRICAL CHARACTERISTICS

3.1 RATING CURRENT: 0.5 A

3.2 RATING VOLTAGE: 30V DC

3.3 CONTACT RESISTANCE: 100 mΩ MAX

3.4 INSULATION RESISTANCE: 1000MΩ MIN

4.5 DIELECTRIC WITHSTANDING VOLTAGE: 500V AC

4.6 OPERATING TEMPERATURE: -40°C ~ +75°C

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS
OTHERWISE STATED :

Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD.
ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu

DATE: 07/29/25

CHECKED BY: Jacky Chen

DATE: 07/29/25

APPROVED BY: Tony Kao

DATE: 07/29/25

MAT'L

FINISH

SCALE

SHEET NO.

TITLE

MODLE

DWG NO.

PART NO.

CONNECTOR

MICRO SIM CARD CONNECTOR 8PIN

NO-PUSH H1.40mm

MSIM-008-S304

SIZE

A4

VER

R

ITEM NO. DESCRIPTION DRAWN DATE